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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	604
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-6fcn1152i

Architecture Overview

The LatticeSC architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR). The upper left and upper right corners of the devices contain SERDES blocks and their associated PCS blocks, as shown in Figure 2-1.

Top left and top right corner of the device contain blocks of SERDES. Each block of SERDES contains four channels (quad). Each channel contains a single serializer and de-serializer, synchronization and word alignment logic. The SERDES quad connects with the Physical Coding Sub-layer (PCS) blocks that contain logic to simultaneously perform alignment, coding, de-coding and other functions. The SERDES quad block has separate supply, ground and reference voltage pins.

The PICs contain logic to facilitate the conditioning of signals to and from the I/O before they leave or enter the FPGA fabric. The block provides DDR and shift register capabilities that act as a gearbox between high speed I/O and the FPGA fabric. The blocks also contain programmable Adaptive Input Logic that adjusts the delay applied to signals as they enter the device to optimize setup and hold times and ensure robust performance.

sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM, ROM or FIFO. These blocks have dedicated logic to simplify the implementation of FIFOs.

The PFU, PIC and EBR blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. These blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

The corners contain the sysCLOCK Analog Phase Locked Loop (PLL) and Delay Locked Loop (DLL) Blocks. The PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeSC architecture provides eight analog PLLs per device and 12 DLLs. The DLLs provide a simple delay capability and can also be used to calibrate other delays within the device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The system bus simplifies the connections of the external microprocessor to the device for tasks such as SERDES and PCS configuration or interface to the general FPGA logic. The LatticeSC devices use 1.2V as their core voltage operation with 1.0V operation also possible.

toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-9 illustrates the DCS Block diagram.

Figure 2-9. DCS Block Diagram

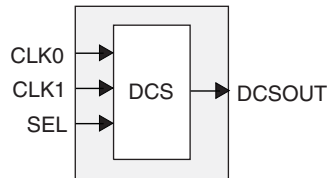
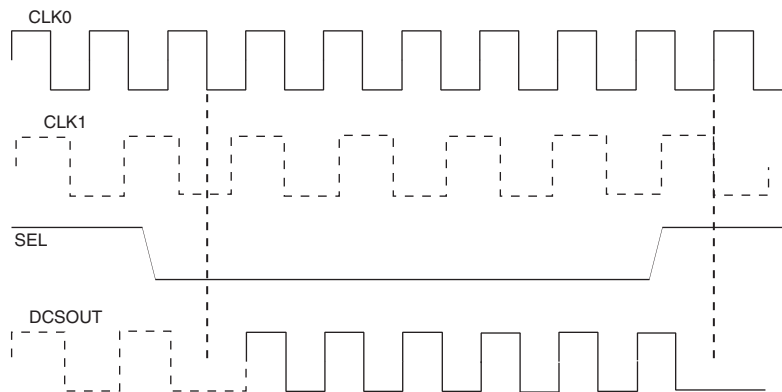


Figure 2-10 shows timing waveforms for one of the DCS operating modes. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-10. DCS Waveforms



Clock Boosting

There are programmable delays available in the clock signal paths in the PFU, PIC and EBR blocks. These allow setup and clock-to-output times to be traded to meet critical timing without slowing the system clock. If this feature is enabled then the design tool automatically uses these delays to improve timing performance.

Global Set/Reset

There is a global set/reset (GSR) network on the device that is distributed to all FFs, PLLs, DLLs and other blocks on the device. This GSR network can operate in two modes:

- a) asynchronous - no clock is required to get into or out of the reset state.
- b) synchronous - The global GSR net is synchronized to a user selected clock. In this mode it continues to be asynchronous to get into the reset state, but is synchronous to get out of the reset state. This allows all registers on the device to become operational in the same clock period. The synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met (not from the GSR being released).

sysCLOCK Phase Locked Loops (PLLs)

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider and two clock output dividers. The input divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal.

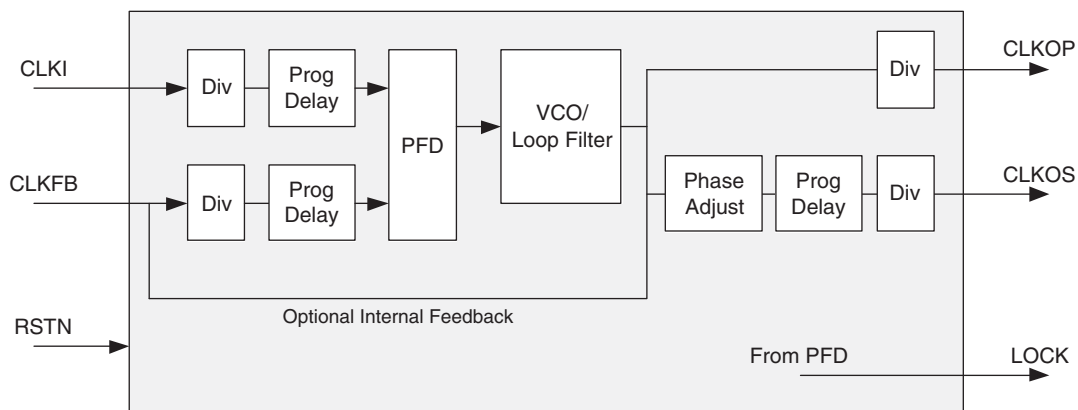
The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically.

The Phase Select block can modify the phase of the clock signal if desired. The Spread Spectrum block supports the modulation of the PLL output frequency. This reduces the peak energy in the fundamental and its harmonics providing for lower EMI (Electro Magnetic Interference).

The sysCLOCK PLL can be configured at power-up and then, if desired, reconfigured dynamically through the serial memory interface bus which connects with the on-chip system bus. For example, the user can select inputs, loop filters, divider setting, delay settings and phase shift settings. The user can also directly access the SMI bus through the routing.

The PLL clock input, from pin or routing, feeds into an input divider. There are four sources of feedback signal to the feedback divider: from the clock net, directly from the voltage controlled oscillator (VCO) output, from the routing or from an external pin. The signal from the input clock divider and the feedback divider are passed through the programmable delay before entering the phase frequency detector (PFD) unit. The output of this PFD is used to control the voltage controlled oscillator. There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-11 shows the sysCLOCK PLL diagram.

Figure 2-11. PLL Diagram



For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Spread Spectrum Clocking (SSC)

The PLL supports spread spectrum clocking to reduce peak EMI by using “down-spread” modulation. The spread spectrum operation will vary the output frequency (at 30KHz to 500KHz) in a range that is between its nominal value, down to a frequency that is a programmable 1%, 2%, or 3% lower than normal.

Digital Locked Loop (DLLs)

In addition to PLLs, the LatticeSC devices have up to 12 DLLs per device. DLLs assist in the management of clocks and strobes. DLLs are well suited to applications where the clock may be stopped or transferring jitter from input to output is important, for example forward clocked interfaces. PLLs are good for applications requiring the lowest output jitter or jitter filtering. All DLL outputs are routed as primary/edge clock sources.

The DLL has two independent clock outputs, CLKOP and CLKOS. These outputs can individually select one of the outputs from the tapped delay line. The CLKOS has optional fine phase shift and divider blocks to allow this output to be further modified, if required. The fine phase shift block allows the CLKOS output to be phase shifted a further 45, 22.5 or 11.25 degrees relative to its normal position. LOCK output signal is asserted when the DLL is locked. The ALU HOLD signal setting allows users to freeze the DLL at its current delay setting.

Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the PURESPEED I/O buffers. The block contains a register for SDR operation and a group of three registers for DDR and shift register operation. The output signal tri-state control signal (TO) can be derived directly from one of the inputs (bypass mode), the SDR shift register, the DDR registers or the data associated with the buffer (for open drain emulation). Figure 2-24 shows the diagram of the Tristate Register Block.

Tristate SDR Register/Latch Block

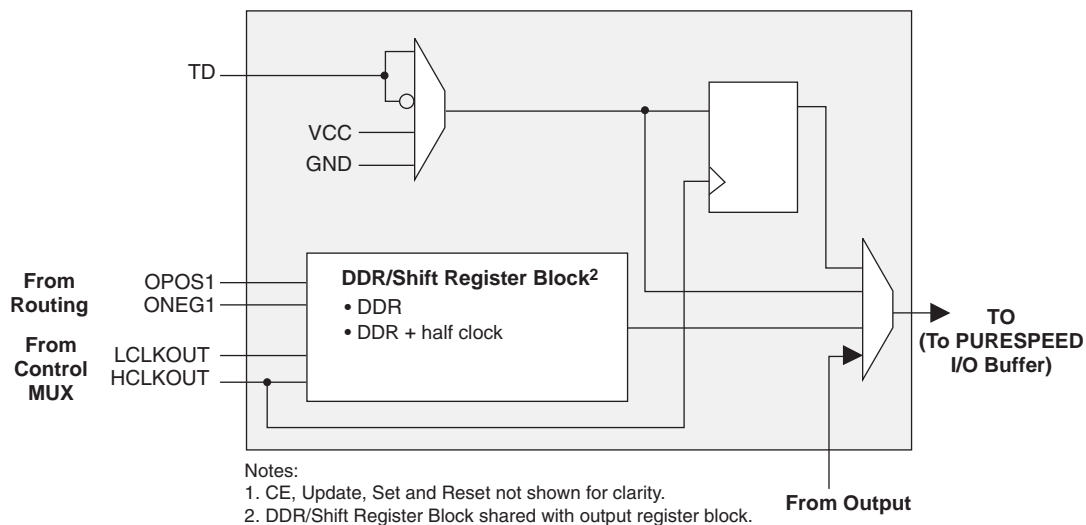
The SDR register operates on the positive edge of the high-speed clock. In it has a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR and Global Set Reset GSR enable or disable. The register LSR input is driven from LSRO, which is generated from the PIO control MUX. The GSR input is driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

Tristate DDR/Shift Register Block

The DDR/Shift block is shared with the output block allowing DDR support using the high-speed clock and the associated transfer from the low-speed clock domain. It functions as a gearbox allowing low-speed parallel data from the FPGA fabric to provide a high-speed tri-state control stream.

There is a special mode for DDR-II memory interfaces where the termination is controlled by the output tristate signal. During WRITE cycle when the FPGA is driving the lines, the parallel terminations are turned off. During READ cycle when the FPGA is receiving data, the parallel terminations are turned on.

Figure 2-24. Tristate Register Block¹



I/O Architecture Rules

Table 2-6 shows the PIO usage for x1, x2, x4 gearing. The checkmarks in the columns show the specific PIOs that are used for each gearing mode. When using x2 or x4 gearing, any PIO which is not used for gearing can still be used as an output.

Differential Input Termination

The LatticeSC device allows two types of differential termination. The first is a single resistor across the differential inputs. The second is a center-tapped system where each input is terminated to the on-chip termination bus V_{CMT} . The V_{CMT} bus is DC-coupled through an internal capacitor to ground.

Figure 2-29 shows the differential termination schemes and Table 2-9 shows the nominal values of the termination resistors.

Figure 2-29. Differential Termination Scheme

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Differential termination		
Differential and common mode termination		

Calibration

There are two calibration sources that are associated with the termination scheme used in the LatticeSC devices:

- DIFFR – This pin occurs in each bank that supports differential drivers and must be connected through a 1K+/-1% resistor to ground if differential outputs are used. Note that differential drivers are not supported in banks 1, 4 and 5.
- XRES – There is one of these pins per device. It is used for several functions including calibrating on-chip termination. This pin should always be connected through a 1K+/-1% resistor to ground.

The LatticeSC devices support two modes of calibration:

- Continuous – In this mode the SC devices continually calibrate the termination resistances. Calibration happens several times a second. Using this mode ensures that termination resistances remain calibrated as the silicon junction temperature changes.
- User Request – In this mode the calibration circuit operates continuously. However, the termination resistor values are only updated on the assertion of the calibration_update signal available to the core logic.

For more information on calibration, refer to the details of additional technical documentation at the end of this data sheet.

Hot Socketing

The LatticeSC devices have been carefully designed to ensure predictable behavior during power-up and power-down. To ensure proper power sequencing, care must be taken during power-up and power-down as described below. During power-up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits,

VDDAX25 needs to be connected independent of the use of the SERDES. This supply is used to control the SERDES CML I/O regardless of the SERDES being used in the design.

Supported Source Synchronous Interfaces

The LatticeSC devices contain a variety of hardware, such as delay elements, DDR registers and PLLs, to simplify the implementation of Source Synchronous interfaces. Table 2-11 lists Source Synchronous and DDR/QDR standards supported in the LatticeSC. For additional detail refer to technical information at the end of the data sheet.

Table 2-11. Source Synchronous Standards Table¹

Source Synchronous Standard	Clocking	Speeds (MHz)	Data Rate (Mbps)
RapidIO	DDR	500	1000
SPI4.2 (POS-PHY4)/NPSI	DDR	500	1000
SFI4/XSBI	DDR SDR	334 667	667
XGMII	DDR	156.25	312
CSIX	SDR	250	250
QDRII/QDRII+ memory interface	DDR	300	600
DDR memory interface	DDR	240	480
DDRII memory interface	DDR	333	667
RLDRAM memory interface	DDR	400	800

1. Memory width is dependent on the system design and limited by the number of I/Os in the device.

flexiPCS™ (Physical Coding Sublayer Block)

flexiPCS Functionality

The LatticeSC family combines a high-performance FPGA fabric, high-performance I/Os and large embedded RAM in a single industry leading architecture. LatticeSC devices also feature up to 32 channels of embedded SERDES with associated Physical Coding Sublayer (PCS) logic. The flexiPCS logic can be configured to support numerous industry standard high-speed data transfer protocols.

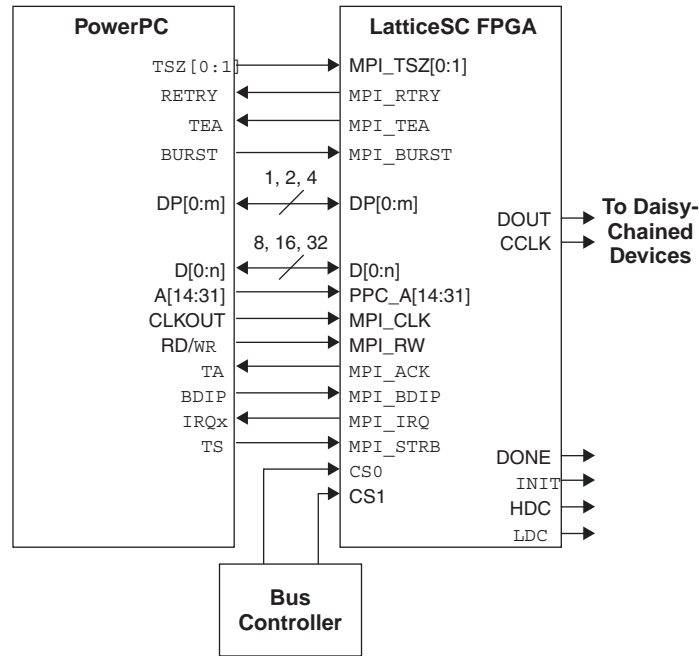
Each channel of flexiPCS logic contains dedicated transmit and receive SERDES for high-speed, full-duplex serial data transfers at data rates up to 3.8 Gbps. The PCS logic in each channel can be configured to support an array of popular data protocols including SONET (STS-12/STS-12c, STS-48/STS-48c, and TFI-5 support of 10 Gbps or above), Gigabit Ethernet (compliant to the IEEE 100BASE-X specification), 1.02 or 2.04 Gbps Fibre Channel, PCI-Express, and Serial RapidIO. In addition, the protocol based logic can be fully or partially bypassed in a number of configurations to allow users flexibility in designing their own high-speed data interface.

Protocols requiring data rates above 3.8 Gbps can be accommodated by dedicating either one pair or all four channels in one flexiPCS quad block to one data link. One quad can support full-duplex serial data transfers at data rates up to 15.2 Gbps. A single flexiPCS quad can be configured to support 10Gb Ethernet (with a fully compliant XAUI interface), 10Gb Fibre Channel, and x4 PCI-Express and 4x RapidIO.

The flexiPCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic which can also be geared to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic. Each SERDES pin can be DC coupled independently and can allow for both high-speed and low-speed operation down to DC rates on the same SERDES pin, as required by some Serial Digital Video applications.

The ispLEVER design tools from Lattice support all modes of the flexiPCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow a user to define their own operation. With ispLEVER, the user can define the mode for each quad in a design. Nine modes are currently supported by the ispLEVER design flow:

Figure 2-32. PowerPCI and MPI Schematic



Configuration and Testing

The following section describes the configuration and testing features of the LatticeSC family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeSC devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS33, 25 and 18 standards. For additional detail refer to technical information at the end of the data sheet.

Device Configuration

All LatticeSC devices contain three possible ports that can be used for device configuration. The serial port, which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration. The MPI port supports 8-bit, 16-bit or 32-bit configuration.

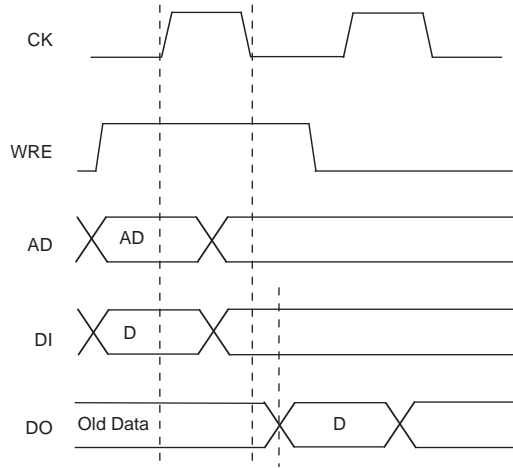
The serial port supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins. When sysCONFIG mode is not used, these dual-use pins are available for general purpose I/O. All I/Os for the sysCONFIG and MPI ports are in I/O bank #1.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next re-initialization sequence. For additional detail refer to technical information at the end of the data sheet.

Timing Diagrams

PFU Timing Diagrams

Figure 3-4. Slice Single/Dual Port Write Cycle Timing



Notes:

- Rising Edge for latching WREN, WAD and DATAIN.
- WREN must continue past falling edge clock.
- Data output occurs on negative edge.

Figure 3-5. Slice Single/Dual Port Read Cycle Timing

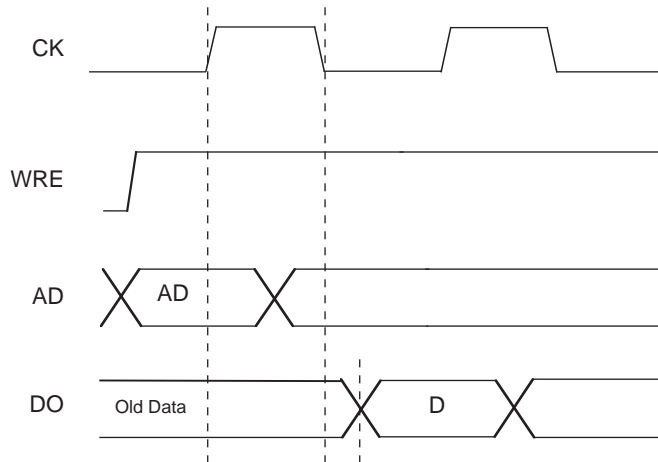
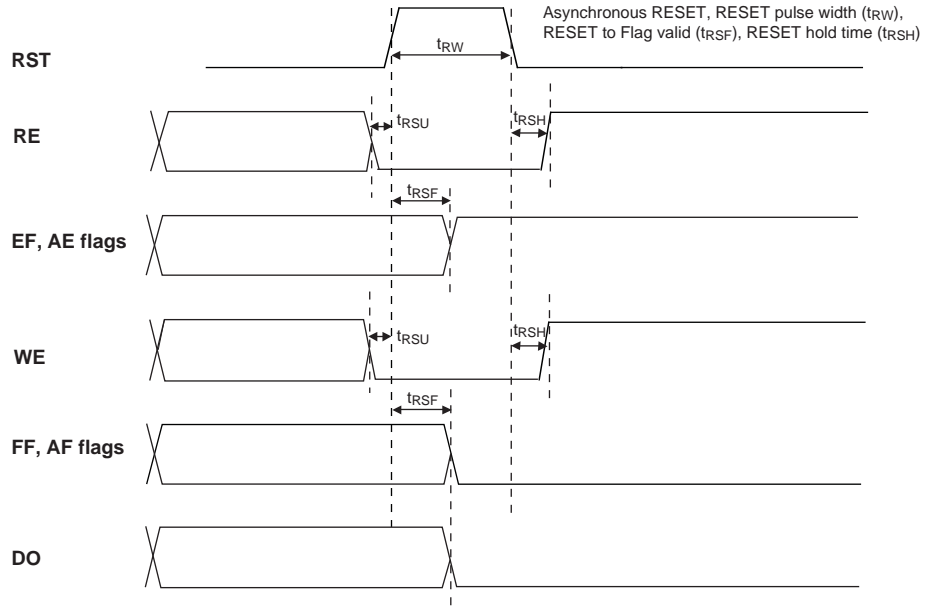
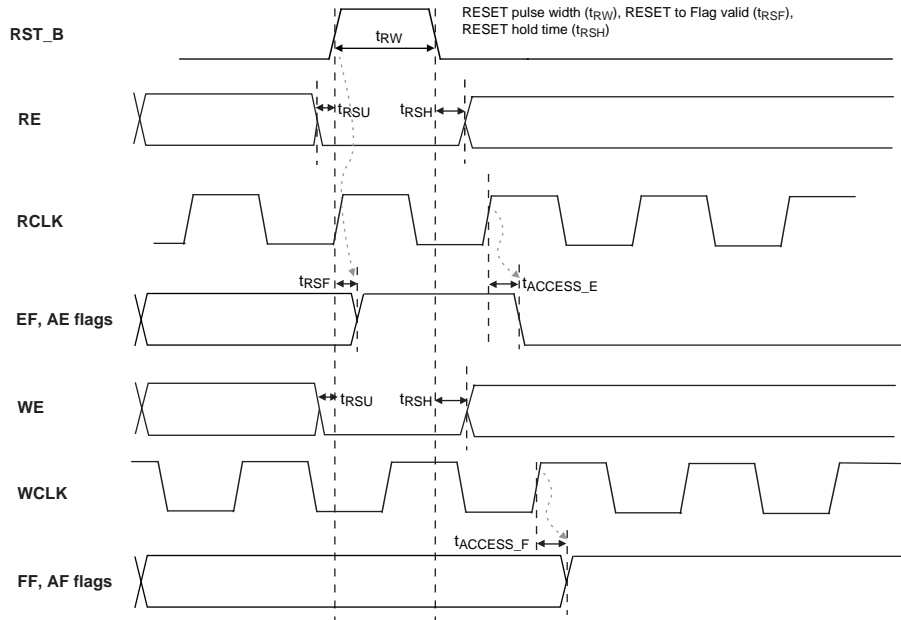


Figure 3-10. FIFO Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Figure 3-11. Read Pointer Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

LatticeSC/M sysCONFIG Port Timing (Continued)

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Asynchronous Peripheral Configuration Mode				
t_{WRAP}	WRN, CS0N and CS1 Pulse Width	5	-	ns
t_{SAP}	D[7:0] Setup Time	1.5	-	ns
t_{RDYAP}	RDY Delay	—	8	ns
t_{BAP}	RDY Low	1	8	CCLK periods
t_{WR2AP}	Earliest WRN After RDY Goes High	0	—	ns
t_{DENAP}	RDN to D[7:0] Enable/Disable	—	7.5	ns
t_{DAP}	CCLK to DOUT	—	7.5	ns
sysCONFIG Slave Serial Configuration Mode				
t_{SSS}	DIN Setup Time	5.2	—	ns
t_{HSS}	DIN Hold Time	0	—	ns
t_{CHSS}	CCLK High Time	3.75	—	ns
t_{CLSS}	CCLK Low Time	3.75	—	ns
f_{CSS}	CCLK Frequency	—	150	MHz
t_{DSS}	CCLK to DOUT	—	7.5	ns
sysCONFIG Slave Parallel Configuration Mode				
t_{S1SP}	CS0N, CS1, WRN Setup Time	5.2	—	ns
t_{H1SP}	CS0N, CS1, WRN Hold Time	0	—	ns
t_{S2SP}	D[7:0] Setup Time	5.2	—	ns
t_{H2SP}	D[7:0] Hold Time	0	—	ns
t_{CHSP}	CCLK High Time	3.75	—	ns
t_{CL}	CCLK Low Time	3.75	—	ns
f_{CSP}	CCLK Frequency	—	150	MHz

sysCONFIG MPI Port

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{MPICTRL_SET}$	MPI Control (MPCSTRBN, MPCWRN, MPCCLK, etc.) to MPCCLK Setup Time	4.9	—	5.2	—	5.5	—	ns
t_{MPIADR_SET}	MPI Address to MPCCLK Setup Time	3.9	—	4.2	—	4.5	—	ns
t_{MPIDAT_SET}	MPI Write Data to MPCCLK Setup Time	4.9	—	5.2	—	5.5	—	ns
$t_{MPIDPAR_SET}$	MPI Write Parity Data to MPCCLK Setup Time	3.9	—	4.2	—	4.5	—	ns
t_{MPI_HLD}	All Hold Times	0	—	0	—	0	—	ns
$t_{MPICTRL_DEL}$	MPCCLK to MPI Control (MPCTA, MPC-TEA, MPCRETRY)	—	5.6	—	6.7	—	8.7	ns
t_{MPIDAT_DEL}	MPCCLK to MPI Data	—	5.6	—	6.7	—	8.7	ns
$t_{MPIDPAR_DEL}$	MPCCLK to MPI Parity Data	—	4.9	—	5.7	—	7.7	ns
$f_{MPI_CLK_FRQ}$	MPCCLK Frequency	—	100	—	83	—	66	MHz

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
R29	PR28B	3		PR31B	3	
P29	PR28A	3		PR31A	3	
P27	PR27C	3	PCLKT3_3	PR30C	3	PCLKT3_3
N29	PR27B	3		PR30B	3	
N28	PR27A	3		PR30A	3	
R25	PR26D	3	PCLKC3_1	PR29D	3	PCLKC3_1
R26	PR26C	3	PCLKT3_1	PR29C	3	PCLKT3_1
R28	PR26B	3	PCLKC3_0	PR29B	3	PCLKC3_0
P28	PR26A	3	PCLKT3_0	PR29A	3	PCLKT3_0
N27	PR24D	2	PCLKC2_2	PR27D	2	PCLKC2_2
P26	PR24C	2	PCLKT2_2	PR27C	2	PCLKT2_2
L30	PR24B	2	PCLKC2_0	PR27B	2	PCLKC2_0
K30	PR24A	2	PCLKT2_0	PR27A	2	PCLKT2_0
J30	PR23B	2	PCLKC2_1	PR26B	2	PCLKC2_1
H30	PR23A	2	PCLKT2_1	PR26A	2	PCLKT2_1
M26	PR22D	2	DIFFR_2	PR25D	2	DIFFR_2
M25	PR22C	2	VREF1_2	PR25C	2	VREF1_2
G29	PR22B	2		PR25B	2	
F29	PR22A	2		PR25A	2	
H28	PR19D	2		PR22D	2	
J28	PR19C	2		PR22C	2	
E30	PR19B	2		PR22B	2	
E29	PR19A	2		PR22A	2	
L26	PR18D	2	VREF2_2	PR18D	2	VREF2_2
L25	PR18C	2		PR18C	2	
F28	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G28	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
K26	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
K25	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
D30	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
D29	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
G26	PR15D	2		PR16D	2	
H26	PR15C	2		PR16C	2	
E28	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
D28	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
J25	VCCJ	-		VCCJ	-	
H25	TDO	-	TDO	TDO	-	TDO
J26	TMS	-		TMS	-	
G25	TCK	-		TCK	-	
G24	TDI	-		TDI	-	
F26	PROGRAMN	1		PROGRAMN	1	
H24	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
F25	CCLK	1		CCLK	1	
D27	VCC12	-		VCC12	-	
E26	VCC12	-		VCC12	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AM21	PB29A	5		PB38A	5	
AM20	PB29B	5		PB38B	5	
AH21	PB29C	5		PB38C	5	
AH20	PB29D	5		PB38D	5	
AJ18	PB31A	5		PB39A	5	
AK18	PB31B	5		PB39B	5	
AH19	PB31C	5		PB39C	5	
AH18	PB31D	5		PB39D	5	
AL19	PB32A	5		PB41A	5	
AM19	PB32B	5		PB41B	5	
AH17	PB32C	5		PB41C	5	
AG17	PB32D	5		PB41D	5	
AL18	PB33A	5		PB42A	5	
AM18	PB33B	5		PB42B	5	
AC17	PB33C	5		PB42C	5	
AD17	PB33D	5		PB42D	5	
AL17	PB35A	5		PB43A	5	
AM17	PB35B	5		PB43B	5	
AE17	PB35C	5		PB43C	5	
AF17	PB35D	5		PB43D	5	
AM16	PB37A	4		PB45A	4	
AL16	PB37B	4		PB45B	4	
AF16	PB37C	4		PB45C	4	
AE16	PB37D	4		PB45D	4	
AM15	PB38A	4		PB46A	4	
AL15	PB38B	4		PB46B	4	
AD16	PB38C	4		PB46C	4	
AC16	PB38D	4		PB46D	4	
AM14	PB39A	4		PB47A	4	
AL14	PB39B	4		PB47B	4	
AG16	PB39C	4		PB47C	4	
AH16	PB39D	4		PB47D	4	
AK15	PB41A	4		PB49A	4	
AJ15	PB41B	4		PB49B	4	
AH15	PB41C	4		PB49C	4	
AH14	PB41D	4		PB49D	4	
AM13	PB42A	4		PB50A	4	
AM12	PB42B	4		PB50B	4	
AH13	PB42C	4		PB50C	4	
AH12	PB42D	4		PB50D	4	
AK14	PB43A	4		PB51A	4	
AJ14	PB43B	4		PB51B	4	
AE15	PB43C	4		PB51C	4	
AD15	PB43D	4		PB51D	4	
AL13	PB46A	4	PCLKT4_2	PB53A	4	PCLKT4_2
AL12	PB46B	4	PCLKC4_2	PB53B	4	PCLKC4_2
AG14	PB46C	4	PCLKT4_7	PB53C	4	PCLKT4_7
AG13	PB46D	4	PCLKC4_7	PB53D	4	PCLKC4_7
AM11	PB47A	4	PCLKT4_1	PB54A	4	PCLKT4_1
AM10	PB47B	4	PCLKC4_1	PB54B	4	PCLKC4_1

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
L1	PR31A	2		PR43A	2	
T10	PR30D	2		PR42D	2	
U10	PR30C	2		PR42C	2	
N2	PR30B	2		PR42B	2	
M2	PR30A	2		PR42A	2	
R11	PR29D	2		PR37D	2	
P11	PR29C	2		PR37C	2	
N4	PR29B	2		PR37B	2	
M4	PR29A	2		PR37A	2	
N5	PR27D	2		PR35D	2	
M5	PR27C	2		PR35C	2	
L2	PR27B	2		PR35B	2	
K2	PR27A	2		PR35A	2	
P8	PR26D	2		PR33D	2	
N8	PR26C	2		PR33C	2	
J2	PR26B	2		PR33B	2	
H2	PR26A	2		PR33A	2	
M6	PR25D	2		PR31D	2	
L6	PR25C	2		PR31C	2	
K3	PR25B	2		PR31B	2	
J3	PR25A	2		PR31A	2	
M8	PR23D	2	DIFFR_2	PR29D	2	DIFFR_2
L8	PR23C	2	VREF1_2	PR29C	2	VREF1_2
K4	PR23B	2		PR29B	2	
J4	PR23A	2		PR29A	2	
M7	PR22D	2		PR21D	2	
L7	PR22C	2		PR21C	2	
J5	PR22B	2		PR21B	2	
H5	PR22A	2		PR21A	2	
N9	PR21D	2		PR20D	2	
P9	PR21C	2		PR20C	2	
G3	PR21B	2		PR20B	2	
F3	PR21A	2		PR20A	2	
J6	PR18D	2	VREF2_2	PR18D	2	VREF2_2
H6	PR18C	2		PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR16D	2		PR16D	2	
H7	PR16C	2		PR16C	2	
G5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
W7	GND	-	
AA14	VCC	-	
AA16	VCC	-	
AA17	VCC	-	
AA18	VCC	-	
AA19	VCC	-	
AA21	VCC	-	
AB13	VCC	-	
AB22	VCC	-	
N13	VCC	-	
N22	VCC	-	
P14	VCC	-	
P16	VCC	-	
P17	VCC	-	
P18	VCC	-	
P19	VCC	-	
P21	VCC	-	
R15	VCC	-	
R17	VCC	-	
R18	VCC	-	
R20	VCC	-	
T14	VCC	-	
T16	VCC	-	
T19	VCC	-	
T21	VCC	-	
U14	VCC	-	
U15	VCC	-	
U17	VCC	-	
U18	VCC	-	
U20	VCC	-	
U21	VCC	-	
V14	VCC	-	
V15	VCC	-	
V17	VCC	-	
V18	VCC	-	
V20	VCC	-	
V21	VCC	-	
W14	VCC	-	
W16	VCC	-	
W19	VCC	-	
W21	VCC	-	
Y15	VCC	-	
Y17	VCC	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AP8	PB117D	4		PB131D	4	
AY3	PB119A	4		PB133A	4	
AW3	PB119B	4		PB133B	4	
AR6	PB119C	4		PB133C	4	
AR5	PB119D	4		PB133D	4	
AU5	PB120A	4		PB134A	4	
AV5	PB120B	4		PB134B	4	
AL12	PB120C	4		PB134C	4	
AL11	PB120D	4		PB134D	4	
AV3	PB121A	4		PB135A	4	
AV4	PB121B	4		PB135B	4	
AN9	PB121C	4		PB135C	4	
AN8	PB121D	4		PB135D	4	
AW1	PB123A	4		PB138A	4	
AY1	PB123B	4		PB138B	4	
AK14	PB123C	4	VREF1_4	PB138C	4	VREF1_4
AK13	PB123D	4		PB138D	4	
AV2	PB124A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB139A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AW2	PB124B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB139B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AM10	PB124C	4		PB139C	4	
AM9	PB124D	4		PB139D	4	
AV1	PB125A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB141A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AU1	PB125B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB141B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AL10	PB125C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB141C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AL9	PB125D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB141D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AT3	PROBE_VCC	-		PROBE_VCC	-	
AU2	PROBE_GND	-		PROBE_GND	-	
AP7	PR95D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR117D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AN7	PR95C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR117C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AR3	PR95B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AR4	PR95A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AP6	PR94D	3		PR116D	3	
AN6	PR94C	3		PR116C	3	
AT2	PR94B	3		PR116B	3	
AR2	PR94A	3		PR116A	3	
AM6	PR93D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AL6	PR93C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AP5	PR93B	3		PR115B	3	
AN5	PR93A	3		PR115A	3	
AL8	PR91D	3		PR112D	3	
AK8	PR91C	3		PR112C	3	
AP2	PR91B	3		PR112B	3	
AN2	PR91A	3		PR112A	3	
AJ12	PR90D	3		PR109D	3	
AH12	PR90C	3		PR109C	3	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB6	PR57D	3		PR71D	3	
AA6	PR57C	3		PR71C	3	
Y2	PR57B	3		PR71B	3	
W2	PR57A	3		PR71A	3	
AB7	PR56D	3		PR70D	3	
AA7	PR56C	3		PR70C	3	
Y3	PR56B	3		PR70B	3	
W3	PR56A	3		PR70A	3	
AC11	PR55D	3		PR69D	3	
AB11	PR55C	3	VREF1_3	PR69C	3	VREF1_3
Y4	PR55B	3		PR69B	3	
W4	PR55A	3		PR69A	3	
AB8	PR52D	3	PCLKC3_2	PR66D	3	PCLKC3_2
AA8	PR52C	3	PCLKT3_2	PR66C	3	PCLKT3_2
Y5	PR52B	3		PR66B	3	
W5	PR52A	3		PR66A	3	
AC12	PR51D	3	PCLKC3_3	PR65D	3	PCLKC3_3
AB12	PR51C	3	PCLKT3_3	PR65C	3	PCLKT3_3
V1	PR51B	3		PR65B	3	
U1	PR51A	3		PR65A	3	
W7	PR50D	3	PCLKC3_1	PR64D	3	PCLKC3_1
V7	PR50C	3	PCLKT3_1	PR64C	3	PCLKT3_1
V2	PR50B	3	PCLKC3_0	PR64B	3	PCLKC3_0
U2	PR50A	3	PCLKT3_0	PR64A	3	PCLKT3_0
AB9	PR48D	2	PCLKC2_2	PR62D	2	PCLKC2_2
AA9	PR48C	2	PCLKT2_2	PR62C	2	PCLKT2_2
T1	PR48B	2	PCLKC2_0	PR62B	2	PCLKC2_0
R1	PR48A	2	PCLKT2_0	PR62A	2	PCLKT2_0
AB10	PR47D	2	PCLKC2_3	PR61D	2	PCLKC2_3
AA10	PR47C	2	PCLKT2_3	PR61C	2	PCLKT2_3
U3	PR47B	2	PCLKC2_1	PR61B	2	PCLKC2_1
T3	PR47A	2	PCLKT2_1	PR61A	2	PCLKT2_1
Y9	PR46D	2		PR60D	2	
W9	PR46C	2		PR60C	2	
V5	PR46B	2		PR60B	2	
U5	PR46A	2		PR60A	2	
AA11	PR43D	2		PR57D	2	
Y11	PR43C	2		PR57C	2	
Y6	PR43B	2		PR57B	2	
W6	PR43A	2		PR57A	2	
Y10	PR42D	2		PR56D	2	
W10	PR42C	2		PR56C	2	
T2	PR42B	2		PR56B	2	
R2	PR42A	2		PR56A	2	
W8	PR41D	2		PR55D	2	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B22	PT61B	1	A3/MPI_ADDR17	PT69B	1	A3/MPI_ADDR17
B23	PT61A	1	A4/MPI_ADDR18	PT69A	1	A4/MPI_ADDR18
K23	PT60D	1	D25/PCLKC1_5/MPI_DATA25	PT66D	1	D25/PCLKC1_5/MPI_DATA25
J23	PT60C	1	D26/PCLKT1_5/MPI_DATA26	PT66C	1	D26/PCLKT1_5/MPI_DATA26
D22	PT60B	1	A5/MPI_ADDR19	PT66B	1	A5/MPI_ADDR19
E22	PT60A	1	A6/MPI_ADDR20	PT66A	1	A6/MPI_ADDR20
K22	PT59D	1	D27/MPI_DATA27	PT63D	1	D27/MPI_DATA27
J22	PT59C	1	VREF1_1	PT63C	1	VREF1_1
D23	PT59B	1	A7/MPI_ADDR21	PT63B	1	A7/MPI_ADDR21
C23	PT59A	1	A8/MPI_ADDR22	PT63A	1	A8/MPI_ADDR22
L23	PT57D	1	D28/PCLKC1_6/MPI_DATA28	PT61D	1	D28/PCLKC1_6/MPI_DATA28
M23	PT57C	1	D29/PCLKT1_6/MPI_DATA29	PT61C	1	D29/PCLKT1_6/MPI_DATA29
A24	PT57B	1	A9/MPI_ADDR23	PT61B	1	A9/MPI_ADDR23
B24	PT57A	1	A10/MPI_ADDR24	PT61A	1	A10/MPI_ADDR24
K25	PT56D	1	D30/PCLKC1_7/MPI_DATA30	PT58D	1	D30/PCLKC1_7/MPI_DATA30
J25	PT56C	1	D31/PCLKT1_7/MPI_DATA31	PT58C	1	D31/PCLKT1_7/MPI_DATA31
F23	PT56B	1	A11/MPI_ADDR25	PT58B	1	A11/MPI_ADDR25
F22	PT56A	1	A12/MPI_ADDR26	PT58A	1	A12/MPI_ADDR26
J26	PT55D	1	D11/MPI_DATA11	PT57D	1	D11/MPI_DATA11
K26	PT55C	1	D12/MPI_DATA12	PT57C	1	D12/MPI_DATA12
E23	PT55B	1	A13/MPI_ADDR27	PT57B	1	A13/MPI_ADDR27
E24	PT55A	1	A14/MPI_ADDR28	PT57A	1	A14/MPI_ADDR28
G23	PT53D	1	A16/MPI_ADDR30	PT55D	1	A16/MPI_ADDR30
G24	PT53C	1	D13/MPI_DATA13	PT55C	1	D13/MPI_DATA13
F26	PT53B	1	A15/MPI_ADDR29	PT55B	1	A15/MPI_ADDR29
F27	PT53A	1	A17/MPI_ADDR31	PT55A	1	A17/MPI_ADDR31
H25	PT52D	1	A19/MPI_TSIZ1	PT54D	1	A19/MPI_TSIZ1
H24	PT52C	1	A20/MPI_BDIP	PT54C	1	A20/MPI_BDIP
C25	PT52B	1	A18/MPI_TSIZ0	PT54B	1	A18/MPI_TSIZ0
C26	PT52A	1	MPI_TEA	PT54A	1	MPI_TEA
K24	PT51D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
J24	PT51C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F24	PT51B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
F25	PT51A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
L26	D_REFCLKP_L	-		D_REFCLKP_L	-	
M26	D_REFCLKN_L	-		D_REFCLKN_L	-	
G27	VCC12	-		VCC12	-	
C29	D_VDDIB3_L	-		D_VDDIB3_L	-	
F28	VCC12	-		VCC12	-	
D26	D_HDINP3_L	-	PCS 363 CH 3 IN P	D_HDINP3_L	-	PCS 363 CH 3 IN P
E26	D_HDINN3_L	-	PCS 363 CH 3 IN N	D_HDINN3_L	-	PCS 363 CH 3 IN N
B25	D_HDOUTP3_L	-	PCS 363 CH 3 OUT P	D_HDOUTP3_L	-	PCS 363 CH 3 OUT P
D24	VCC12	-		VCC12	-	
A25	D_HDOUTN3_L	-	PCS 363 CH 3 OUT N	D_HDOUTN3_L	-	PCS 363 CH 3 OUT N
E25	D_VDDOB3_L	-		D_VDDOB3_L	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH22	VTT_5	5		VTT_5	5	
AJ22	VTT_5	5		VTT_5	5	
AJ23	VTT_5	5		VTT_5	5	
AJ24	VTT_5	5		VTT_5	5	
AJ25	VTT_5	5		VTT_5	5	
AB28	VTT_6	6		VTT_6	6	
AB29	VTT_6	6		VTT_6	6	
AE29	VTT_6	6		VTT_6	6	
AJ30	VTT_6	6		VTT_6	6	
AA28	VTT_7	7		VTT_7	7	
AA29	VTT_7	7		VTT_7	7	
R31	VTT_7	7		VTT_7	7	
V29	VTT_7	7		VTT_7	7	
Y24	GND	-		GND	-	
Y26	GND	-		GND	-	
Y8	GND	-		GND	-	
Y35	GND	-		GND	-	
AA16	VCC12	-		VCC12	-	
AA27	VCC12	-		VCC12	-	
AB16	VCC12	-		VCC12	-	
AB27	VCC12	-		VCC12	-	
AF16	VCC12	-		VCC12	-	
AF27	VCC12	-		VCC12	-	
AG17	VCC12	-		VCC12	-	
AG21	VCC12	-		VCC12	-	
G33	NC	-		NC	-	
G10	NC	-		NC	-	
M15	NC	-		NC	-	
L15	NC	-		NC	-	
K16	NC	-		NC	-	
J16	NC	-		NC	-	
M18	NC	-		NC	-	
L18	NC	-		NC	-	
M25	NC	-		NC	-	
L25	NC	-		NC	-	
J27	NC	-		NC	-	
K27	NC	-		NC	-	
L28	NC	-		NC	-	
M28	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M80 and LatticeSC/M115 in a 1704-pin package supports a 32-bit MPI interface.

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-7FC1152C ¹	-7	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-6FC1152C ¹	-6	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-5FC1152C ¹	-5	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-7FF1152C	-7	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-6FF1152C	-6	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-5FF1152C	-5	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-7FC1704C ¹	-7	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-6FC1704C ¹	-6	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-5FC1704C ¹	-5	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-7FF1704C	-7	Organic fcBGA	1704	COM	80.1
LFSC3GA80E-6FF1704C	-6	Organic fcBGA	1704	COM	80.1
LFSC3GA80E-5FF1704C	-5	Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-7FC1152C ¹	-7	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FC1152C ¹	-6	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FC1152C ¹	-5	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FF1152C	-7	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FF1152C	-6	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FF1152C	-5	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FC1704C ¹	-7	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FC1704C ¹	-6	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FC1704C ¹	-5	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-7FF1704C	-7	Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FF1704C	-6	Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FF1704C	-5	Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152C ¹	-6	Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-5FC1152C ¹	-5	Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSC3GA115E-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSC3GA115E-6FC1704C ¹	-6	Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-5FC1704C ¹	-5	Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSC3GA115E-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.			
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include I_{DUTY} .
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.